NOTES:
1) R19 for test purposes only

ASSEMBLY:
C11b to C15b backpacked
L2 does not meet pattern

Revision History

<table>
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<th>Revision</th>
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<tr>
<td>A</td>
<td>*** preliminary ***</td>
</tr>
<tr>
<td>B</td>
<td>loop/spoiler/RFET/Cin</td>
</tr>
<tr>
<td>C</td>
<td>added input filter vs reflected ripple</td>
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Designed for: Public Release
Project Title: Telecom block converter w/ TPS40170

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